2SD1439

Silicon NPN Triple-Diffused Junction Mesa Type

Horizontal Deflection Output

■ Features

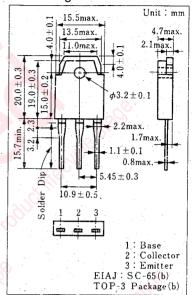
- Damper diode built-in
- High breakdown voltage and high reliability by glass passivation
- High speed switching
- Wide area of safety operation (ASO)

■ Absolute Maximum Ratings (Tc=25°C)

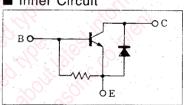
Symbol	Value	Unit
V _{CBO}	1500	V
VCES	1500	V
AEBO	5	v
Ic	3	A
I _{CP} *	10	A 90
I _{BP}	3.5	A
I _{BP}	-2.5	A
. D	50	college and
r _C	2.5	W
T_{i}	130	C C
Tstg	$-55 \sim +130$	C)
	VCBO VCES VEBO IC ICP* IBP IBP TC Tc	VCBO 1500 VCES 1500 VEBO 5 IC 3 ICP* 10 IBP 3.5 IBP -2.5 PC 2.5 Tj 130

^{*} Non repetitive peak value

■ Package Dimensions

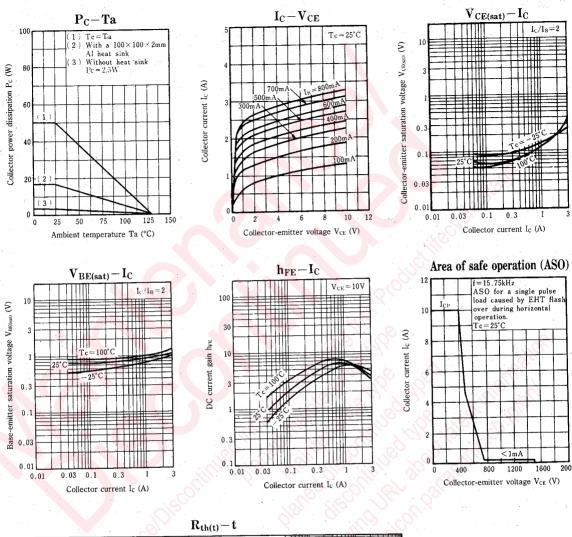


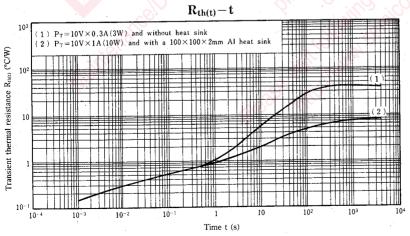
■ Inner Circuit



■ Electrical Characteristics (Tc=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 750 \text{ V}, I_E = 0$	0,,,		50	μA
		$V_{CB} = 1500 \text{ V}, I_E = 0$			1	mA
Emitter-base voltage	V _{EBO}	$I_E = 500 \text{ mA}, I_C = 0$	5			V
DC current gain	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ A}$	4		12	·
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 2 A, I_B = 0.75 A$		1	5	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 2 \text{ A}, I_B = 0.75 \text{ A}$			1.5	V
Transition frequency	f_{T}	$V_{CE} = 10V, I_{C} = 0.5A, f = 0.5MHz$		2	,	MHz
Fall time	t _f	$I_C = 2A$, $I_{Bend} = 0.75A$			0.75	μς
Storage time	t _{stg}	$L_{\text{leak}} = 5 \mu \text{ H}$	3		7	μs
Diode forward voltage	VF	$V_{CE} = 10V$, $I_{C} = 0.5A$, $f = 0.5MHz$			-2.2	V





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